

電鍍／蝕刻用 溶解剝膜型DFR

Dry Film Photoresist with Soluble Stripping

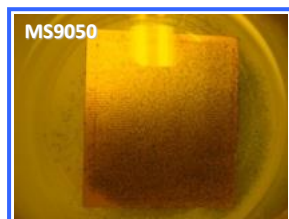
MS9000 Series

➤ 特徴

- 適用於蝕刻／電鍍製程
- 優異的剝膜表現



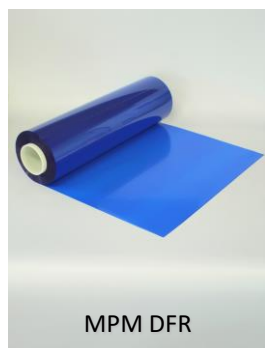
剝膜
(NaOH)



光阻層

持續不斷裂解並溶於一般剝膜液中 (3% NaOH, 50℃)

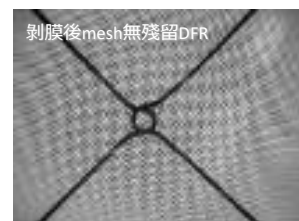
- 基板貼附力佳,適用於SUS/銅合金/Si/玻璃/PI等表面貼附
- 蝕刻／電鍍藥水耐久性佳



MPM DFR



離型膜



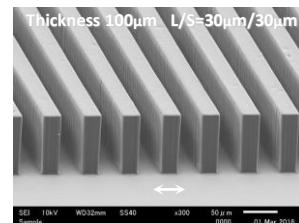
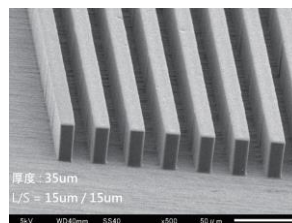
剝膜後mesh無殘留DFR

Type	Thickness	Exposure	Resolution
MS9025	25 μm	15~50 mJ/cm^2	20/20 μm
MS9050	50 μm		40/40 μm

MSP4000 Series

➤ 特徴

- 特別適用於細線路電鍍製程
- 1:2.5高縱深比立膜
- 基板貼附力佳
適用於SUS/銅合金/Si/玻璃/PI等表面貼附
- 立膜表現優異
- 優異的剝膜表現
- 蝕刻／電鍍藥水耐久性佳



Item	MSP4015	MSP4035	MSP4050	MSP4050 x2 Lamination
Thickness	15 μm	35 μm	50 μm	100 μm
Exposure	55 mJ/cm^2	55 mJ/cm^2	60 mJ/cm^2	60 mJ/cm^2
Resolution	10/10 μm	15/15 μm	20/20 μm	30/30 μm